



Material Content Data Sheet



Sales Product Name		IR3889MTRPBF		Issued		3. July 2019		
MA#		MA005341252						
Package		PG-IQFN-36-2		Weight*		105.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.552	1.47	1.47	14733	14733
chip_2	inorganic material	silicon	7440-21-3	0.690	0.66	0.66	6553	6553
chip_3	inorganic material	silicon	7440-21-3	0.200	0.19	0.19	1894	1894
leadframe	inorganic material	phosphorus	7723-14-0	0.012	0.01		111	
	non noble metal	zinc	7440-66-6	0.047	0.04		443	
	non noble metal	iron	7439-89-6	0.933	0.89		8860	
wire	non noble metal	copper	7440-50-8	37.891	35.97	36.91	359750	369164
	noble metal	gold	7440-57-5	0.381	0.36	0.36	3613	3613
	encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		744
encapsulation	plastics	epoxy resin	-	4.036	3.83		38320	
	inorganic material	silicondioxide	60676-86-0	35.072	33.30	37.20	332978	372042
	leadfinish	noble metal	palladium	7440-05-3	0.003	0.00		29
leadfinish	noble metal	gold	7440-57-5	0.005	0.00		47	
	non noble metal	nickel	7440-02-0	0.091	0.09	0.09	860	936
	plating	noble metal	silver	7440-22-4	0.248	0.24	0.24	2359
solder	noble metal	silver	7440-22-4	0.087	0.08		829	
	non noble metal	tin	7440-31-5	0.175	0.17		1658	
	non noble metal	lead	7439-92-1	3.231	3.07	3.32	30671	33158
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.006	0.01		59	
	non noble metal	zinc	7440-66-6	0.025	0.02		235	
	non noble metal	iron	7439-89-6	0.494	0.47		4693	
	non noble metal	copper	7440-50-8	20.071	19.06	19.56	190561	195548
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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